



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

This application is a continuation of:

Serial No. 10/265,210 filed October 4, 2002.

Applicant(s): Borgstrom, Alan D. et al.

Examiner: Paumen, Gary F.

Serial No.:

10/734,786

Group Art Unit: 2833

Filed: December 12, 2003

Docket: 577-549 CON

For: THERMOPL

THERMOPLASTIC MOLDED SET

Dated: June 1, 2004

SCREW CONNECTOR ASSEMBLY

Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

I hereby certify this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia

22313-1450 on June 1, 2004.

By: Kim Tillman Kym Sellower

## RESPONSE PURSUANT TO 37 CFR § 1.111 TO NON-FINAL OFFICE ACTION

Sir:

In response to the Office Action mailed May 13, 2004, a reply which is due August 13, 2004, please consider the following remarks.